

Heterogeneous 3D Integration Key Enabling Technology

Dresden to host summit on latest insights for semiconductor manufacturing and applications

DRESDEN, Germany – 21 January, 2019 – SEMI Europe starts the new year off with the **3D & Systems Summit** from January 28-30, 2019 in Dresden, Germany. The industry will gather for the latest insights and developments in 3D integration and systems for semiconductor manufacturing and applications. Registration at: <http://www1.semi.org/eu/3d-systems-summit-register>

SEMI 3D & Systems Summit will feature a broader scope of topics aimed at driving innovation and business opportunities, including:

- 3DIC Through-Silicon-Via (TSV) technology
- 2.5D, 3D FO-WLP/e-WLB
- Active and passive interposers
- Stacked dies or stacked wafers
- 3D alternative technologies
- 5G Integration



Keynotes



Professor Hubert Lakner, director, **Fraunhofer-Institute for Photonic Microsystems IPMS**, will kick off the summit with his keynote *Heterointegration – The Path to Future Complex Intelligent Systems*. Lakner will explore connected intelligence opportunities arising from the transition to autonomous driving, the digitalization and electrification of cars, and the digitalization of industry and electrical power grids. These capabilities will be enabled by artificial intelligence (AI), improved cybersecurity, reinforced connectivity through 5G, edge computing, low-power components, sensors and power management.



Steffen Kroehnert, Senior Director Technology Development, **Amkor Technology Inc.** will discuss the advancements in heterogeneous integration. The latest wave of technology in the Semiconductor Industry is largely based on artificial intelligence (AI), deep learning, cloud computing and IoT. Each of these leading-edge technologies share a common need: high-speed signaling with ultra low latency/power and real time computational formulations. This requires fully integrated functionality at the source, better known as the edge.

Speaker Lineup:

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3D & Systems Summit speakers include experts from companies such as **Orbotech**, [Corning Inc.](#), **GLOBALFOUNDRIES**, **Fraunhofer-Institute for Photonic Microsystems IPMS**, [EPIC – European Photonics Industry Consortium](#), **McKinsey**, **System Plus Consulting**, **ASE Group**, **imec**, **DISCO HI-TEC EUROPE**, [OeC SA](#), **STMicroelectronics**, **G-ray**, **Amkor**, **TU Dresden**, **Huawei**, **Fraunhofer IZM**, **AT&S AG**, **Deca Technologies** and **Miland**.



Exhibition:

ASE Group, Amkor Technology, Canon, Confovis, DISCO, FineTech, Fraunhofer IZM, FRT Metrology, Imec, LPKF, Optim Wafer Services, SPTS, XPERI, and many more. The exhibition will showcase the most prominent names in 3D integration microelectronics manufacturing. See the floorplan [here](#).

3D & Systems Summit attendees are also invited to join the **Symposium Panel Level Packaging 2019**, organized by Fraunhofer IZM, 30 January 14:00-18:00. To register for the event, please click [here](#). More details are available [here](#).

More information on the 3D & Systems Summit is available [here](#).

About SEMI

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